LAYERED PRESSURE SENSITIVE TRANSDUCER AND METHOD FOR MAKING SAME

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Abstract

A variable resistance transducer responsive to an applied pressure is disclosed comprising a smooth resistive layer on a flexible substrate and deposited thereon by printing or imaging technology, small points of nonconductive or semiconductive material.

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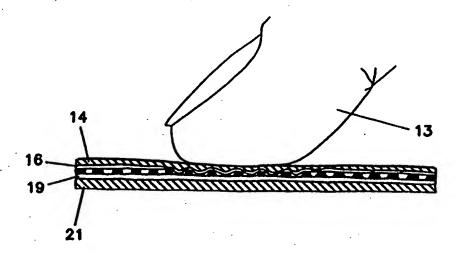
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A variable resistance transducer responsive to an applied pressure is disclosed comprising a smooth resistive layer on a flexible substrate and deposited thereon by printing or imaging technology, small points of nonconductive or semiconductive material.